



Material Content Data Sheet



Sales Product Name		BSC0909NS		Issued		22. January 2018		
MA#		MA001615310						
Package		PG-TDSON-8-40		Weight*		111.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.614	0.55	0.55	5507	5507
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		437	
	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	copper	7440-50-8	48.649	43.66	43.71	436499	437070
wire	non noble metal	copper	7440-50-8	0.055	0.05	0.05	495	495
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		762	
	plastics	epoxy resin	-	6.713	6.02		60228	
	inorganic material	silicondioxide	60676-86-0	35.687	32.02	38.12	320201	381191
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13638	13638
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1422	1422
solder	noble metal	silver	7440-22-4	0.024	0.02		219	
	non noble metal	tin	7440-31-5	0.020	0.02		175	
	non noble metal	lead	7439-92-1	0.932	0.84	0.88	8361	8755
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.02		152	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		46	
	non noble metal	copper	7440-50-8	16.910	15.17	15.19	151724	151922
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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